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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/712,364	11/12/2003	Kazuo Kobayashi	51508/DBP/A400	1459		
23363	7590 08/18/2005		EXAM	EXAMINER		
CHRISTIE, F PO BOX 7068	PARKER & HALE, LLP	COLEMAN, V	COLEMAN, WILLIAM D			
PASADENA, CA 91109-7068			ART UNIT	PAPER NUMBER		
,			2823	2823		
			DATE MAILED: 08/18/2005			

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application	No.	Applicant(s)			
Office Action Summary		10/712,364		KOBAYASHI, KAZUO			
		Examiner		Art Unit			
		W. David Col		2823			
Period f	The MAILING DATE of this communication or Reply	appears on the co	ver sheet with the c	correspondence address			
THE - External control	MAILING DATE OF THIS COMMUNICATION OF THIS COMMUNICATION OF THIS COMMUNICATION OF THIS COMMUNICATION OF THE COMMUN	ON. R 1.136(a). In no event, In. a reply within the statutory criod will apply and will ex tatute, cause the applicati	however, may a reply be tin minimum of thirty (30) day pire SIX (6) MONTHS from ion to become ABANDONE	nely filed s will be considered timely. the mailing date of this communicat D (35 U.S.C. § 133).	ion.		
Status							
1)⊠	Responsive to communication(s) filed on <u>0</u>	07 June 2005.					
·							
3)	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposit	tion of Claims						
5)□ 6)⊠ 7)□	Claim(s) 1-15 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. Claim(s) is/are allowed. Claim(s) 1-15 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or election requirement.						
Applicat	tion Papers						
10)	The specification is objected to by the Exar The drawing(s) filed on is/are: a) Applicant may not request that any objection to Replacement drawing sheet(s) including the co The oath or declaration is objected to by the	accepted or b) the drawing(s) be herection is required in	neld in abeyance. Se if the drawing(s) is ob	e 37 CFR 1.85(a). .jected to. See 37 CFR 1.121			
Priority	under 35 U.S.C. § 119						
12)⊠ a)	Acknowledgment is made of a claim for force All b) Some * c) None of: 1. Certified copies of the priority docum 2. Certified copies of the priority docum 3. Copies of the certified copies of the application from the International Bu See the attached detailed Office action for a	nents have been r nents have been r priority documents ureau (PCT Rule 1	eceived. eceived in Applicat s have been receive 7.2(a)).	ion No ed in this National Stage			
2) Noti	nt(s) ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948 rmation Disclosure Statement(s) (PTO-1449 or PTO/SE er No(s)/Mail Date <u>11/03</u> .	B/08) 5)	Interview Summary Paper No(s)/Mail D Notice of Informal F				

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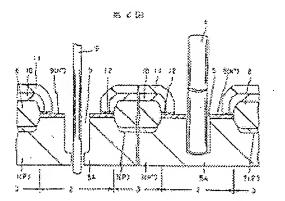
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DETAILED ACTION

Claim Rejections - 35 USC § 102

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

1. Claims 1, 7 and 9 are rejected under 35 U.S.C. 102(b) as being anticipated by Shigeyuki EP 6 329 393 9.



- 1. <u>Shigeyuki</u> teaches a semiconductor process as claimed. See **FIGS. 1-2**, where <u>Shigeyuki</u> teaches the following limitations.
- 2. Pertaining to claim 1, <u>Shigeyuki</u> teaches a substrate machining method for machining a substrate, comprising:

cutting the substrate through a first surface by use of a rotating disk-like blade to produce a cut surface; and

irradiating with laser light an edge of the cut surface of the substrate, that is located in the vicinity of a second surface of the substrate, opposite from the first surface.

3. Pertaining to claim 7, <u>Shigeyuki</u> teaches a substrate machining apparatus for machining a substrate, comprising:

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a disk-like blade that is rotated to cut the substrate through a first surface to produce a cut surface; and

a laser light irradiating portion for irradiating a laser light to the portion, of the cut surface of the substrate, that is located in the vicinity of a second surface of the substrate, opposite from the first surface.

Pertaining to claim 15, <u>Shigeyuki</u> teaches a substrate machining method for machining a substrate, comprising:

cutting the substrate through a first surface by use of a rotating disk-like blade to produce a cut surface; and

Irradiating with laser light an edge of the cut surface of the substrate.

Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claims 3-6 and 9-14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Shigeyuki EP 6 329 393 9 in view of Mulligan et al., U.S. Patent 6,839,200 B2.
- 6. Pertaining to claim 3, Shigeyuki fails to teach a substrate machining method according to claim 1 or 2, wherein the laser is a YAG laser or a CO₂ laser. Mulligan teaches wherein the laser is a YAG or a CO₂ laser. In view of Mulligan, it would have been obvious to one of ordinary

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skill in the art to incorporate a YAG or a CO₂ laser in the <u>Shigeyuki</u> semiconductor process because its ablate away trenches (column 4, line 20).

7. Pertaining to claim 4, Shigeyuki in view of Mulligan teaches a substrate machining method according to claim 1, wherein a dicing tape 116 is adhered to the other surface of the substrate 114; and

the laser light is irradiated after cutting only the substrate and expanding the dicing tape.

- 8. Pertaining to claim 5, Shigeyuki in view of Mulligan teaches a substrate machining method according to claim 1, wherein the laser light is irradiated onto a street that has been already formed and is different from a street being formed by cutting the substrate by the disk-like blade 117.
- 9. Pertaining to claim 6, Shigeyuki in view of Mulligan teaches a substrate machining method according to claim 1, wherein the laser light is irradiated onto a street, that is being formed by cutting the substrate by the disk-like blade, while following the movement of the disk-like blade.
- 10. Pertaining to claim 9, Shigeyuki in view of Mulligan teaches a substrate machining apparatus according to claim 7, wherein the laser light irradiating portion is a YAG laser light irradiating portion or a CO₂ laser light irradiating portion.

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11. Pertaining to claims 12, and 14, Shigeyuki in view of Mulligan teach a substrate machining method according to claims 1 and 7, wherein the substrate is comprised of silicon.

- 12. Claims 2, 8 and 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Shigeyuki EP 6 329 393 9 in view of Hwan et al., U.S. Patent 6,602,762 B2.
- 13. Shigeyuki discloses a semiconductor process substantially as claimed.
- 14. Pertaining to claims 2, 8, 10, 11 and 13, Shigeyuki fails to teach a substrate machining method according to claims 1 and 7, wherein the laser light irradiating portion irradiates the laser light onto all of the cut surface of the substrate. Hwan teaches irradiation all of the cut surface of the substrate (see FIG. 8). In view of Hwan, it would have been obvious to one of ordinary skill in the art to irradiate all of the cut surface of the substrate because the laser beam sinters the serrated edge into a smooth edge (see first sentence in abstract).

Conclusion

- 15. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).
- 16. A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event,

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however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

- 17. Any inquiry concerning this communication or earlier communications from the examiner should be directed to W. David Coleman whose telephone number is 571-272-1856.

 The examiner can normally be reached on Monday-Friday 9:00 AM 5:30 PM.
- 18. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on 571-272-1855. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.
- 19. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

W. David Coleman Primary Examiner Art Unit 2823